

Serial No. 10/627,816
Amdt. dated December 13, 2004
Reply to Office Action of September 13, 2004

Docket No. CIT/K-0139A

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-9. (Canceled).

10. (Currently Amended) ~~In a~~ A method for sealing an organic EL display panel having a multi-layered structure in which a first electrode and a second electrode are formed on a transparent panel and at least one organic EL layer is formed between them, the method for sealing an organic EL display panel comprising the steps of:

forming a buffer layer on the transparent panel; and

locating a shield cover on the buffer layer;

wherein the buffer layer is formed on an entire surface of the transparent panel other than a tap bonding region and a pixel region of the first and second electrodes.

11. (Canceled).

12. (Currently Amended) The method of claim 10 or 19, wherein the buffer layer is formed only on the panel ~~of~~ in a region where the shield cover is located.

13. (Currently Amended) The method of claim 10 or 19, wherein the buffer layer is formed both on the panel ~~of~~ in a region where the shield cover is located and on the electrode ~~of~~ in a region where the shield cover is located.

14. (Currently Amended) The method of claim 10 or 19, wherein the buffer layer ~~of~~ in the region where the shield cover is located has an uneven shape or a dot shape.

15. (Original) The method of claim 14, wherein the dot shaped buffer layer is formed of any one of a round shape, a triangle shape, a quadrangle shape, and a polygonal shape.

16. (Currently Amended) The method of ~~claim 1~~ claim 10 or 19, wherein the buffer layer ~~of~~ in the region where the shield cover is located and the buffer layer ~~of~~ in a region other than the region where the ~~shield~~ shield cover is located have the same material as each other or a different material from each other.

17. (Currently Amended) The method of claim 16, wherein the material of the buffer layer ~~of~~in the region where the shield cover is located is either silicon oxide or silicon nitride, while the material of the buffer layer ~~of~~in the region other than the region where the shield cover is located is any one of silicon oxide, silicon nitride, polyimide, and polyacryl.

18. (Currently Amended) The method of ~~claim 4~~ claim 10 or 19, wherein the buffer layer has a thickness of about 0.1 ~ 5 μ m.

19. (New) A method for sealing an organic EL display panel having a multi-layered structure, a first electrode and a second electrode formed on a transparent panel and an at least one organic EL layer formed between them, comprising the steps of:

forming a buffer layer on an entire surface of the transparent panel other than a tap bonding region and a pixel region of the first and second electrodes;

forming an organic EL layer on the pixel region of the first and second electrodes;

forming an adhesive layer on the buffer layer; and

forming a shield cover on the adhesive layer for protecting the organic EL layer.

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20. (New) A method for sealing an organic EL display panel having a multi-layered structure in which a first electrode and a second electrode are formed on a transparent panel and at least one organic EL layer is formed between them, the method for sealing an organic EL display panel comprising the steps of:

forming a buffer layer on the transparent panel; and

locating a shield cover on the buffer layers;

wherein the buffer layer in the region where the shield cover is located has an uneven shape or a dot shape formed of any one of a round shape, a triangle shape, a quadrangle shape, and a polygonal shape.